

*Abstract of the Disclosure*

A method of removing an optical device contained within a device package from a circuit board, wherein the device package is secured to the circuit board using an adhesive pad. The method includes peeling a portion of the adhesive pad away  
5 from the circuit board, inserting an optical removal tool between the optical device and the circuit board, wherein the optical removal tool has a pair of fork portions and a cavity positioned between the fork portions, and the fork portions straddle one or more leads on the optical device during the inserting step, and prying the remainder of the adhesive pad away from the circuit board using the optical device removal tool.

(b)  
(c)  
(d) 10  
(e)  
(f)  
(g)  
(h)  
(i)  
(j)  
(k)  
(l)  
(m)  
(n)  
(o)  
(p)